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ΡΛΝ	JIT
	SEMI
	CONDUCTOR

### 40V N-Channel Enhancement Mode MOSFET

Voltage

Current 192 A

#### Features

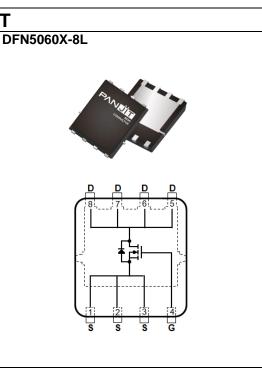
• Rds(on), Vgs@10V, Id@20A<1.88mΩ

40 V

- $R_{DS(ON)}$ ,  $V_{GS}@4.5V$ ,  $I_D@20A<2.5m\Omega$
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

#### **Mechanical Data**

- Case : DFN5060X-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.087 grams



### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETE	R	SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V <sub>DS</sub>	40	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Droin Curront(Note 3)	T <sub>C</sub> =25°C		192	
Continuous Drain Current <sup>(Note 3)</sup>	Tc=100°C	I <sub>D</sub>	136	А
Pulsed Drain Current <sup>(Note 1)</sup>	T <sub>C</sub> =25°C	I <sub>DM</sub>	672	
Devues Disais ation	T <sub>C</sub> =25°C	D-	125	14/
Power Dissipation	Tc=100°C	PD	63	W
Continuous Droin Current(Note 4)	T <sub>A</sub> =25°C		31	٨
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =70°C	ID ID	26	A
Dower Dissinction	T <sub>A</sub> =25°C	Da	3.3	w
Power Dissipation	T <sub>A</sub> =70°C	PD	2.3	٧V
Single Pulse Avalanche Energy <sup>(Note</sup>	9 5)	Eas	462	mJ
Operating Junction and Storage Te	emperature Range	TJ,TSTG	-55~175	°C
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	R <sub>θJC</sub>	1.2	°C/W
mermai Resistancement	Junction to Ambient	R <sub>θJA</sub>	45	



### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static		·				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	-	-	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =50uA	1.1	1.4	2.3	V
Desire Courses On Otate Desistance		V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	1.5	1.88	mΩ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	1.9	2.5	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =40V, $V_{GS}$ =0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Dynamic <sup>(Note 6)</sup>	-	-	-	-	-	-
Total Gate Charge	Qg		-	75	-	
Gate-Source Charge	Qgs	V <sub>DS</sub> =32V, I <sub>D</sub> =20A,	-	15	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	10	-	
Input Capacitance	Ciss		-	4950	-	pF
Output Capacitance	Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	-	1250	-	
Reverse Transfer Capacitance	Crss		-	170	-	
Gate resistance	Rg	f=1MHz	-	1	-	Ω
Turn-On Delay Time	td <sub>(on)</sub>		-	20	-	
Turn-On Rise Time	tr	V <sub>DS</sub> =32V, I <sub>D</sub> =20A,	-	32	-	
Turn-Off Delay Time	td <sub>(off)</sub>	V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω	-	68	-	ns
Turn-Off Fall Time	tf		-	17	-	
Drain-Source Diode	·		•			
Diode Forward Current	Is	T <sub>c</sub> =25°C	-	-	192	
Pulsed Diode Forward Current	I <sub>SM</sub>	Tc=25 C	-	-	672	A
Diode Forward Voltage	V <sub>SD</sub>	Is=20A, V <sub>GS</sub> =0V	-	0.8	1.3	V
Reverse Recovery Time	Trr	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	52	-	ns
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	50	-	nC

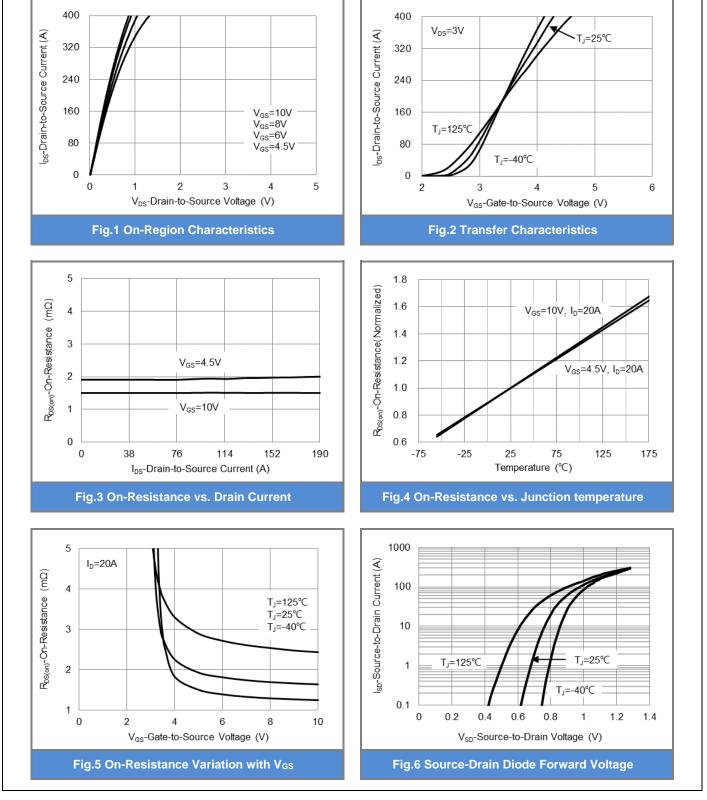
NOTES :

- 1. Pulse width  $\leq$  100 us, Duty cycle  $\leq$  2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an  $R_{\theta JC}=1.2^{\circ}C/W$ , Package limited 100A.
- 4.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I\_{AS}=43A, V\_{DD}=30V, V\_{GS}=10V, Starting T\_J=25 ^{\circ}C.
- 6. Guaranteed by design, not subject to production testing.

April 12,2023

PJQ5540-AU-REV.00





# PJQ5540-AU

**TYPICAL CHARACTERISTIC CURVES** 



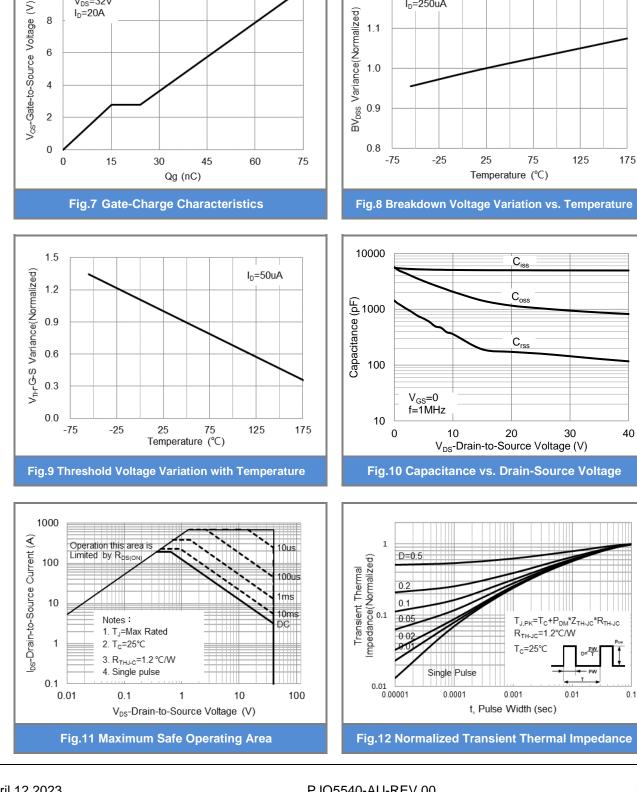


April 12,2023

Page 4

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I<sub>D</sub>=250uA

#### PANJ SEM CONDUCTOR

10

# **PJQ5540-AU**

V<sub>DS</sub>=32V

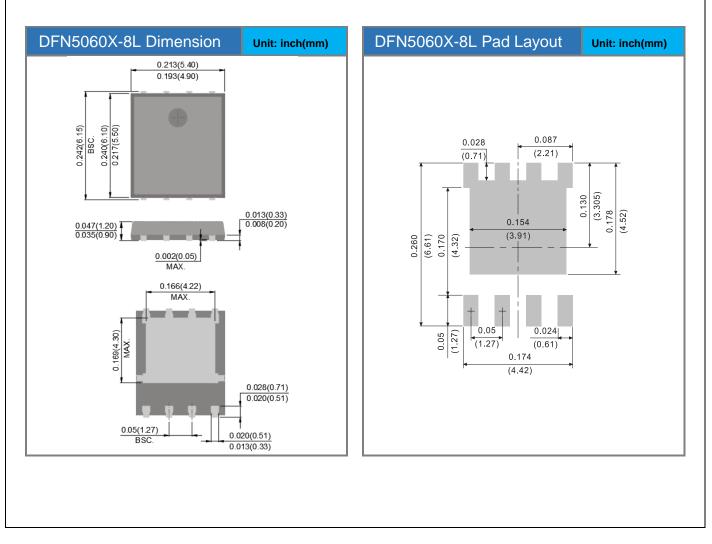
**TYPICAL CHARACTERISTIC CURVES** 



### **Product and Packing Information**

Part No.	Package Type	Packing Type	Marking
PJQ5540-AU	DFN5060X-8L	3K pcs / 13" reel	Q5540

### Packaging Information & Mounting Pad Layout





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